

DIP39, 54.50x31.00x5.60, 1.78P EP-2
CASE MODGX
ISSUE A

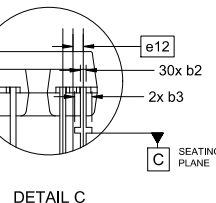
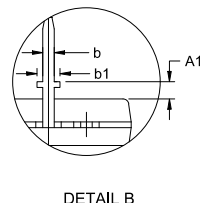
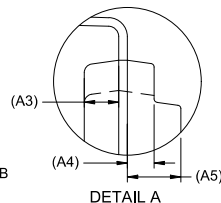
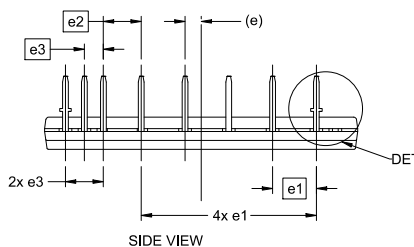
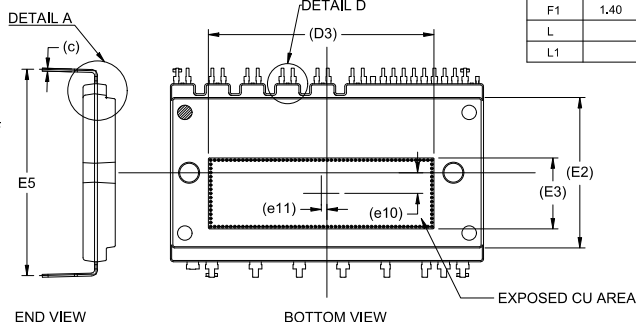
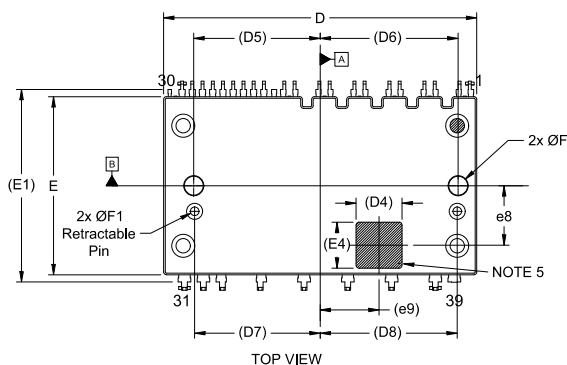
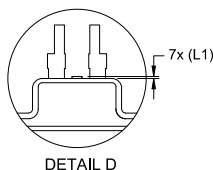
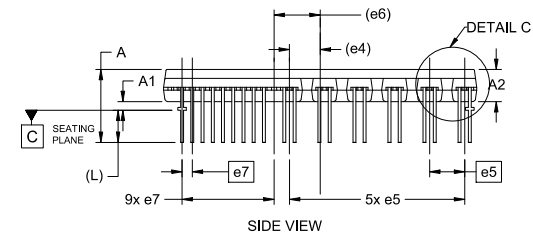
DATE 20 DEC 2023

NOTES:

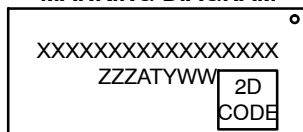
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b and c APPLY TO THE PLATED LEADS AND ARE MEASURED BETWEEN 1.00 AND 2.00 FROM THE LEAD TIP
4. POSITION OF THE LEAD IS DETERMINED AT THE BASE OF THE LEAD WHERE IT EXITS THE PACKAGE BODY
5. AREA FOR 2D BAR CODE
6. SHORTENED/CUT PINS ARE 2,5,8,11,14,17,19,29, 30 AND 39

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	12,20	12,7	13,2
A1	1,00	1,50	2,00
A2	5,50	5,60	5,70
A3		2,00 REF	
A4		1,55 REF	
A5		3,10 REF	
b	0,90	1,00	1,10
b1	1,90	2,00	2,10
b2	0,40	0,50	0,60
b3	1,40	1,50	1,60
c		0,50 REF	
D	54,40	54,50	54,60
D3		39,25 REF	
D4		8,00 REF	
D5		22,00 REF	
D6		24,00 REF	
D7		21,85 REF	
D8		23,85 REF	

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
E	30,90	31,00	31,10
E1		33,50 REF	
E2		26,14 REF	
E3		12,35 REF	
E4		8,00 REF	
E5	35,40	35,90	36,40
e		2,81 REF	
e1		7,62 BSC	
e2		6,60 BSC	
e3		3,30 BSC	
e4		5,35 REF	
e5		6,10 BSC	
e6		8,02 REF	
e7		1,78 BSC	
e8		10,35 REF	
e9		10,25 REF	
e10		3,60 REF	
e11		1,00 REF	
e12		0,89 BSC	
F	3,20	3,30	3,40
F1	1,40	1,50	1,60
L		5,60 REF	
L1		0,10 REF	



GENERIC
MARKING DIAGRAM*



XXXXX = Specific Device Code
ZZZ = Assembly Lot Code
AT = Assembly & Test Location
Y = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON05290H	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	DIP39, 54.50x31.00x5.60, 1.78P EP-2	PAGE 1 OF 1

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.